Abstract

METHOD OF APPLYING ADHESIVE TO LEAD OF LEAD FRAME AND METHOD OF MAKING SEMICONDUCTOR DEVICE USING THE SAME

A method of applying adhesives to leads of lead frame, a nozzle of a dispenser is moved horizontally above one lead and positioned against the lead at a predetermined distance. While keeping adhesives flowing from the nozzle of the dispenser, the dispenser is moved horizontally relative to the leads in a direction from one lead to the next lead so that the distance is kept constant. Then the adhesives are applied to a predetermined portion of each lead. When the application of adhesives to the last lead is complete, the nozzle is raised and moved horizontally. Therefore, the number of upward and downward movements of the nozzle is greatly reduced and the application time can be shortened. Preferably, the distance between the tip of the nozzle and the surface of the lead is to be one-fourth to three times as long as the inside diameter of the nozzle.

Fig. 4